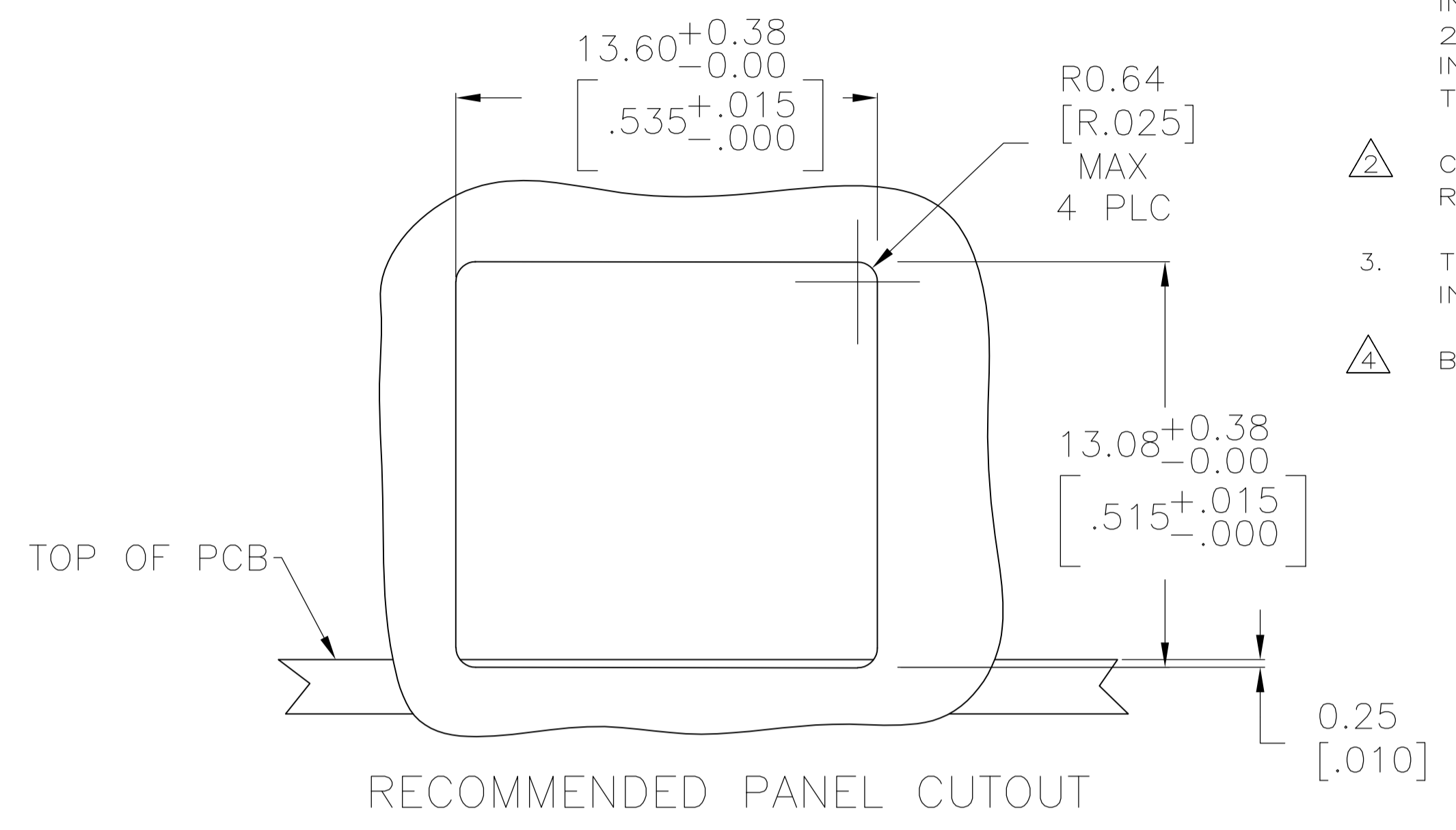
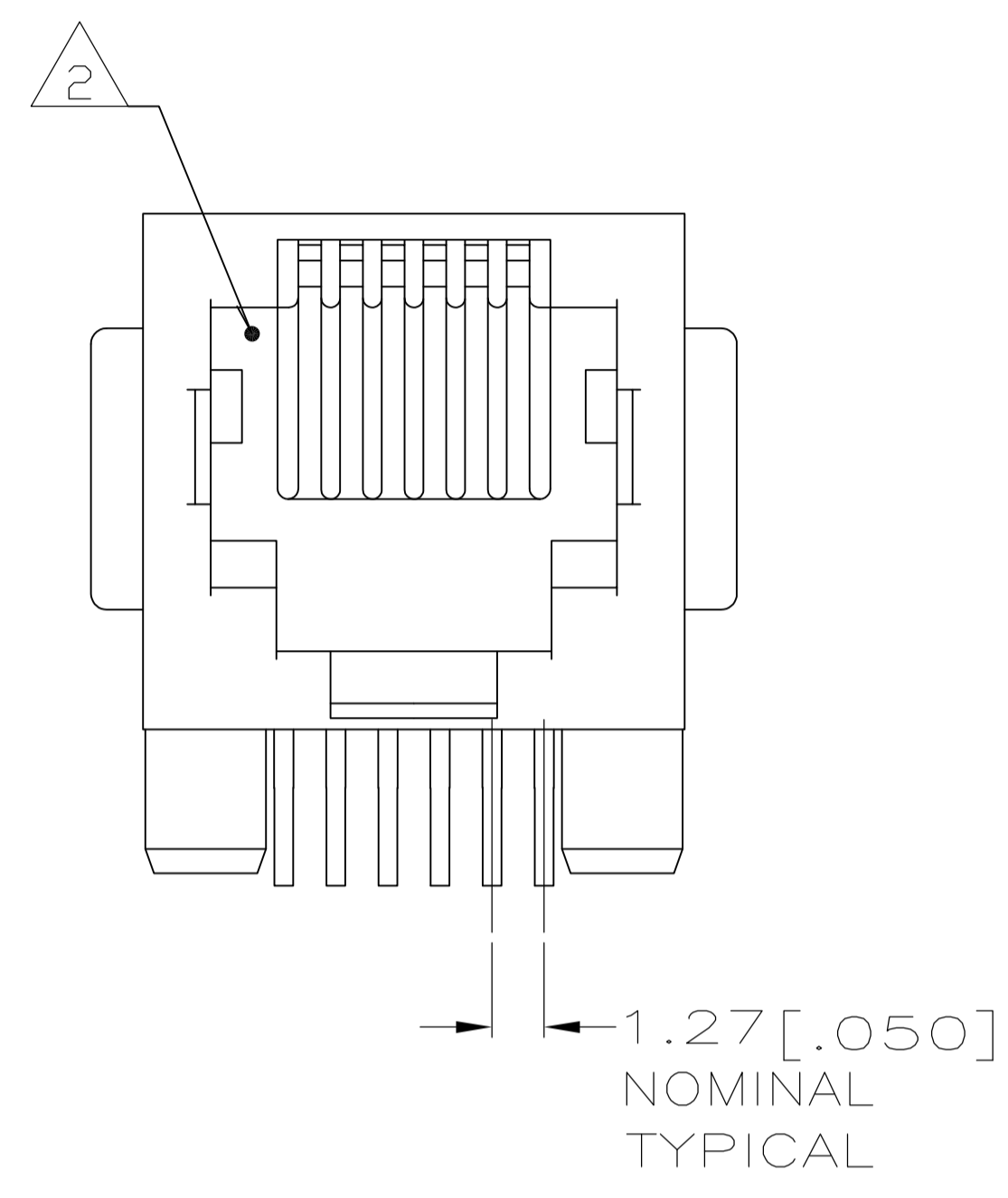
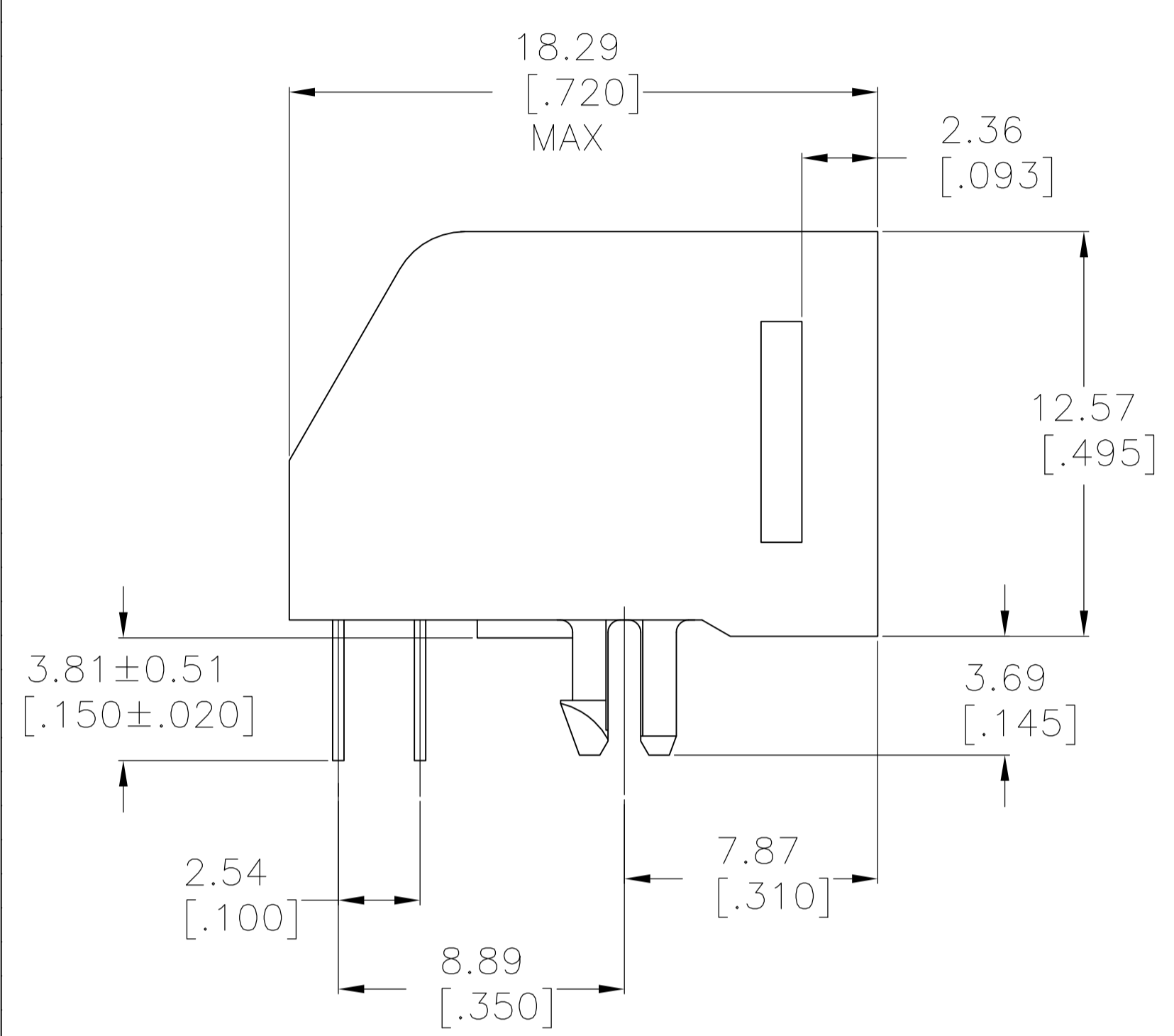
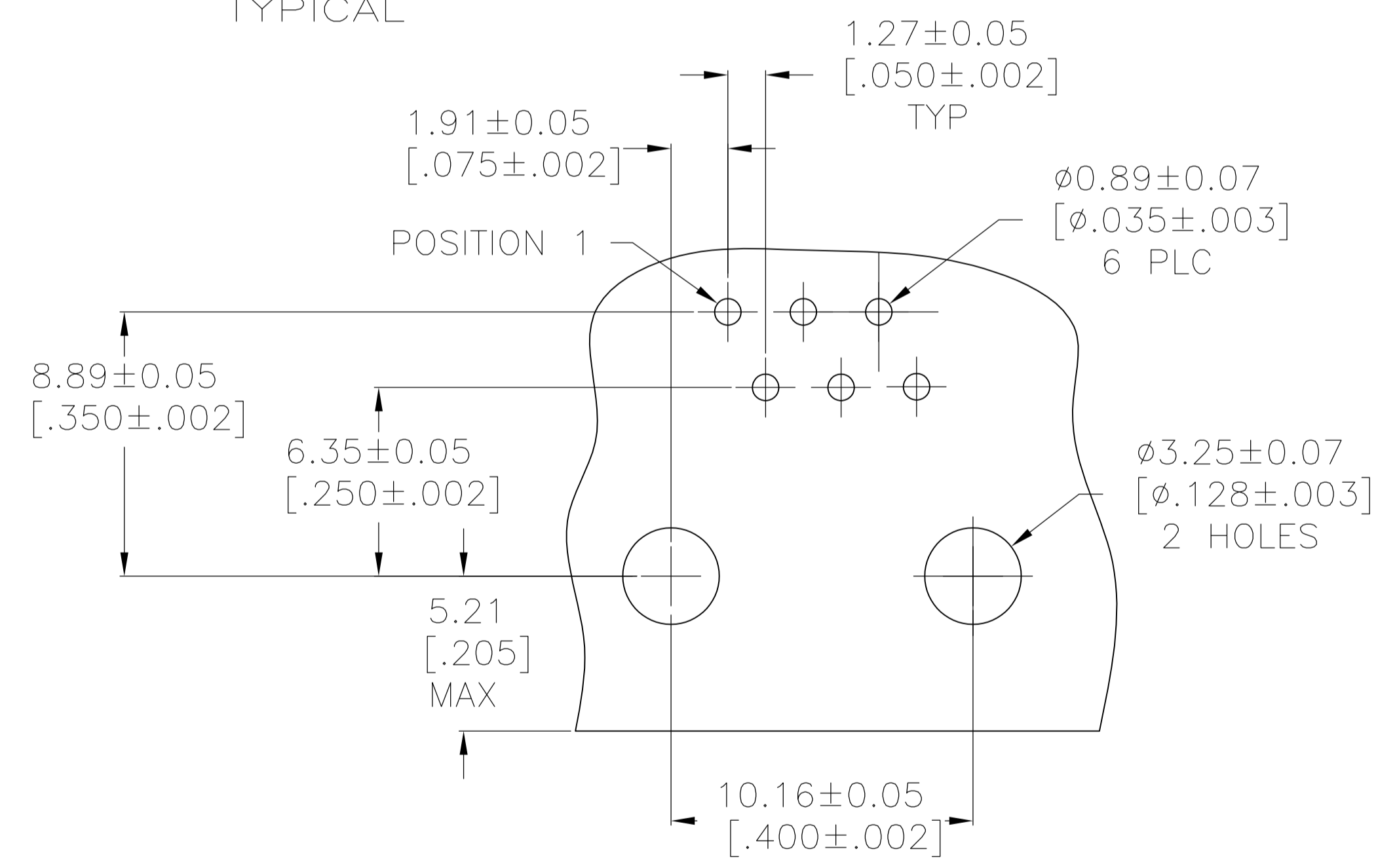
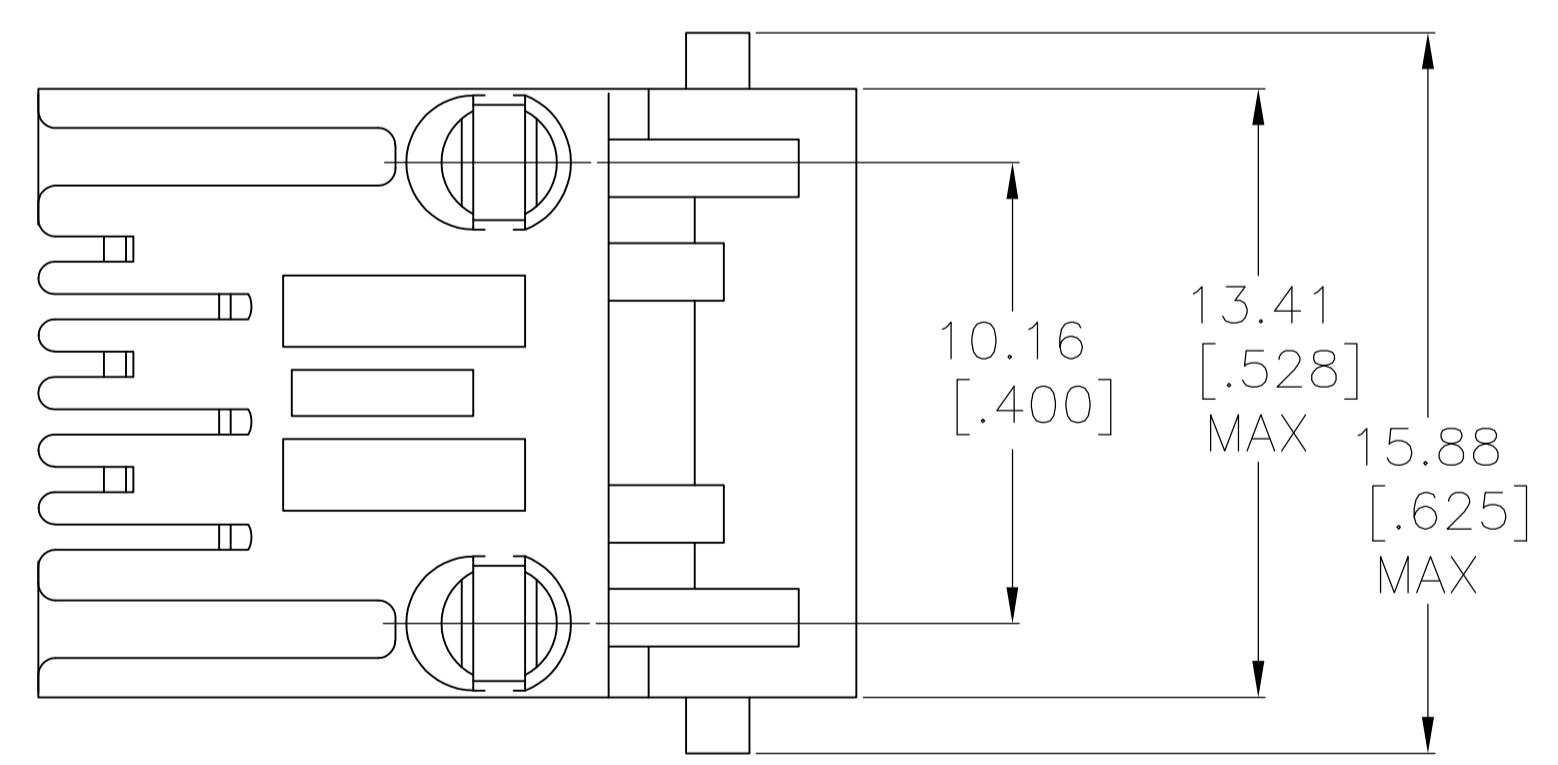


LOC		DIST		REVISIONS			
AA	00	REV	DATE	BY	CHK	APPV	
C1	REVISED PER ECO-11-005140	28MAR11	RK	HMR			



- MATERIAL: HOUSING - PBT POLYESTER, BLACK.
TERMINAL - 0.35 [.0138] THICK PHOSPHOR BRONZE PLATED WITH 1.27µm [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 2.03µm [.000080] THICK MATTE TIN IN SOLDER AREA OVER 1.27µm [.000050] THICK NICKEL UNDERPLATE.
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- TERMINALS FOR 5555163-2 AND -5 LOCATED IN CENTER POSITIONS.
- BULK PACKAGED IN A TRAY.



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SHOWN

REV	DATE	DESCRIPTION	DATE	BY	CHK	APPV
2		5555163-5				
4		5555163-2				
6		5555163-1				

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN G. ATTADIA - 08JUN2005		TE Connectivity	
DIMENSIONS: mm [INCHES]		CHK J. WESTMAN 08JUN2005		NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APPV S. FLICKINGER 08JUN2005		MODULAR JACK ASSEMBLY, 6 POSITION, LOW PROFILE, RIGHT ANGLE, WITH PANEL STOPS	
0 PLC ± -		PRODUCT SPEC		108-1163	
1 PLC ± -		APPLICATION SPEC		114-2048	
2 PLC ± 0.13[.005]		SIZE		A1	
3 PLC ± -		WEIGHT		00779	
4 PLC ± -		CUSTOMER DRAWING		SCALE 6:1	
ANGLES ± -		SHEET 1 OF 1		REV C1	

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)